Claims

1. A two layered gold plating method comprising the steps of : forming a base gold-plated layer ~~of 0.9μm~~ equal to or less than 1.2μm in thickness in which range of less than 0.9μm is excluded on a surface of a metal to be plated as a first plating; and forming a finish gold-plated layer being equal to or less than 0.8μm in thickness as a second plating by an electrolytic method depositing a gold crystal smaller than that of said base gold-plated layer on a surface of said base gold-plated layer.

2. The two layered gold plating method as set forth in claim 1, said finish gold-plated layer is formed with a finish plating liquid in which soluble gold salt or gold complex is dissolved in an aqueous liquid including at least aliphatic amine of 3 to 8 weight percent and organic acid of 3 to 8 weight percent.

~~3.~~ (previously cancelled)

~~4~~3. An electronic component comprising a contact material of which metal to be plated has a gold plated layer formed by a~~said~~ two layered gold plating method, ~~as set forth in claim 1 or 2~~ wherein a base gold-plated layer equal to or less than 1.2μm in thickness in which range of less than 0.9μm is excluded is formed on a surface of said metal to be plated, and wherein a finish gold-plated layer being equal to or less than 0.8μm in thickness formed by an electrolytic method depositing a gold crystal smaller than that of said base gold-plated layer is formed on a surface of said base gold-plated layer.